WHAT IS CLAIMED IS:

1. An electronic device, comprising:

an active device substrate, comprising a substrate, a first wire, and a second wire, wherein the first wire is configured on a first surface of the substrate, the second wire is configured on a second surface of the substrate, ~~and~~ the first surface and the second surface are opposite to each other while a side surface of the substrate connects the first surface to the second surface, an end of the first wire and an end of the second wire are aligned with the side surface of the substrate, and the end of the first wire, the end of the second wire, and the side surface of the substrate are on a same plane;

an insulation film, configured on the side surface of the substrate;

a vertical wire, configured on a surface of the insulation film and located between the insulation film and the side surface of the substrate; and

an anisotropic conductive adhesive, configured between the vertical wire and the side surface of the substrate, and electrically connects the vertical wire to the first wire and the second wire, wherein the anisotropic conductive adhesive is in direct contact with the end of the first wire, the end of the second wire, and the side surface of the substrate.

2. The electronic device according to claim 1, wherein the insulation film has a protrusion portion, and the protrusion portion protrudes away from the vertical wire from an end of the vertical wire.

3. The electronic device according to claim 2, wherein the protrusion portion is bent to cover the end of the vertical wire.

4. The electronic device according to claim 1, further comprising:

a sealing material, configured on the active device substrate and disposed along at least a part of a periphery of the insulation film.

5. The electronic device according to claim 4, wherein one of the insulation film and the sealing material covers an end of the vertical wire.

6. The electronic device according to claim 1, wherein the active device substrate further comprises an insulation layer, the first wire is located between the insulation layer and the substrate, and an edge of the insulation layer is separated from the side surface by a lateral distance.

7. The electronic device according to claim ~~1~~6, wherein ~~an end of the first wire is aligned with the side surface~~ the insulation layer exposes a part of the first wire by separating the edge of the insulation layer from the side surface of the substrate with the lateral distance, so that a length of the part of the first wire corresponds to the lateral distance.

8. The electronic device according to claim ~~1~~2, wherein the protrusion portion of the insulation film does not exceed a top surface of an insulation layer, the insulation layer covers the first wire, and an edge of the insulation layer is separated from the side surface of the substrate by a lateral distance ~~an end of the second wire is aligned with the side surface~~.

9. The electronic device according to claim 1, wherein the anisotropic conductive adhesive extends to contact with a portion of the second wire, and the portion of the second wire extends a lateral distance from the side surface of the substrate ~~is in contact with an end of the first wire and an end of the second wire~~.

10. A manufacturing method of an electronic device, comprising:

forming a vertical wire on a first part of an initial film, and attaching the initial film to an initial substrate, wherein a first wire is formed on a first surface of the initial substrate, and a second part of the initial film covers the first wire;

forming a second wire on a second surface of the substrate, wherein the first surface and the second surface are opposite to each other;

removing an excess part of the initial substrate attached to the first part of the initial film to form an active device substrate, while concurrently exposing the vertical wire and exposing an end of the first wire and an end of the second wire; and

attaching the first part of the initial film to the active device substrate through an

anisotropic conductive adhesive, so that the anisotropic conductive adhesive is in contact with the first wire, the second wire and the vertical wire.

11. The manufacturing method of the electronic device according to claim 10, further comprising:

removing the second part of the initial film and leaving the first part of the initial film to serve as an insulation film attached to the active device substrate.

12. The manufacturing method of the electronic device according to claim 11, further comprising:

disposing a sealing material along at least a part of a periphery of the insulation film.

13. The manufacturing method of the electronic device according to claim 11, further comprising:

bending the insulation film to cover an end of the vertical wire.

14. The manufacturing method of the electronic device according to claim 10, wherein the initial film is attached to the initial substrate through an adhesive.

15. The manufacturing method of the electronic device according to claim 10, wherein the step of removing the excess part of the initial substrate comprises:

cutting the initial substrate and removing the excess part of the initial substrate to form the active device substrate.

16. The manufacturing method of the electronic device according to claim 15, wherein the initial film and the vertical wire remain intact when the initial substrate is cut.

17. The manufacturing method of the electronic device according to claim 10, wherein the initial film is attached to the initial substrate in a manner of displacing the vertical wire by a lateral distance relative to the first wire.

18. The manufacturing method of the electronic device according to claim 10, wherein the first part of the initial film is attached to the active device substrate through the anisotropic conductive adhesive in a manner of aligning the vertical wire with the first wire and

the second wire.

19. The manufacturing method of the electronic device according to claim ~~10~~11, wherein the anisotropic conductive adhesive is in contact with a part of the insulation film that is not disposed with the vertical wire.

20. The manufacturing method of the electronic device according to claim 10, wherein a length of the vertical wire is not less than a distance from the first wire to the second wire.